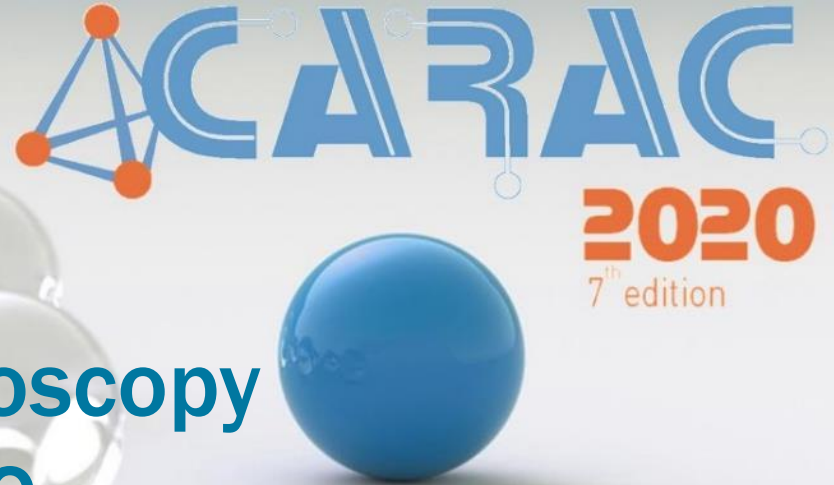


Olivier Renault

Lab-scale Hard X-ray Photoelectron spectroscopy (HAXPES) at the PFNC

23 novembre 2020



- A state-of-the-art characterization platform
- 3 institutes of CEA-Grenoble share instruments & staff scientists
- 80 people
- 50 world-class equipments
- 3000 m² laboratories

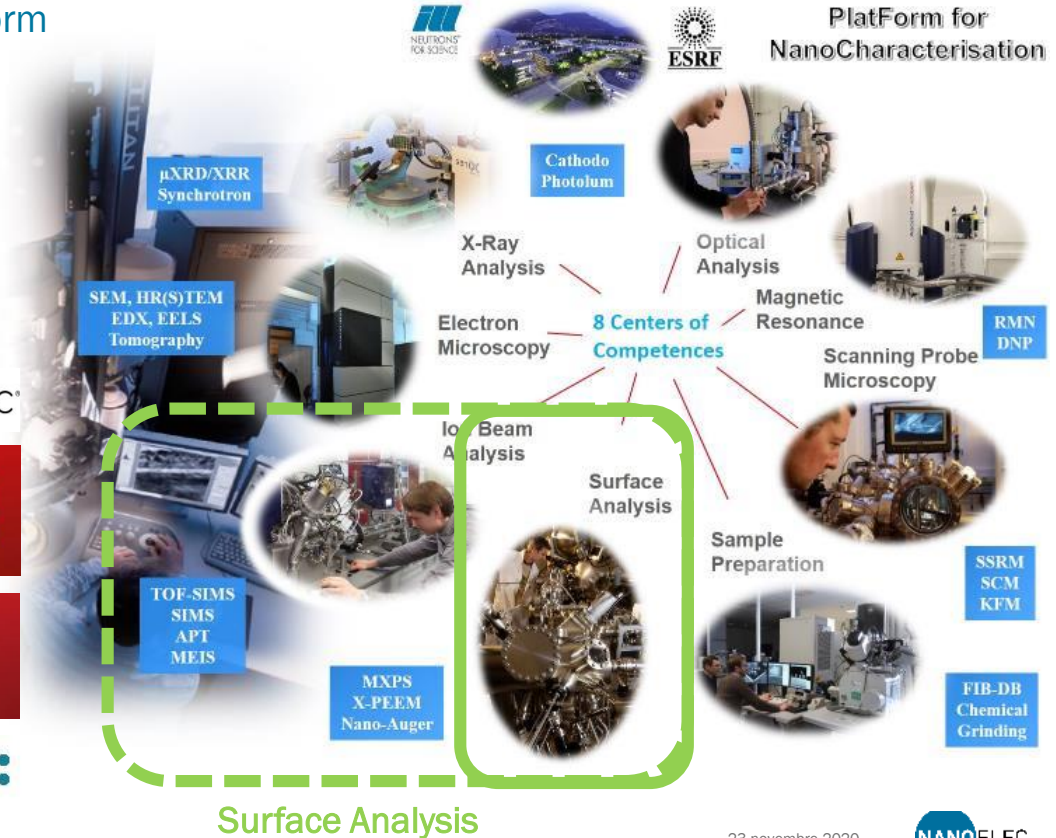


PFNC
MINATEC

leti
cea tech

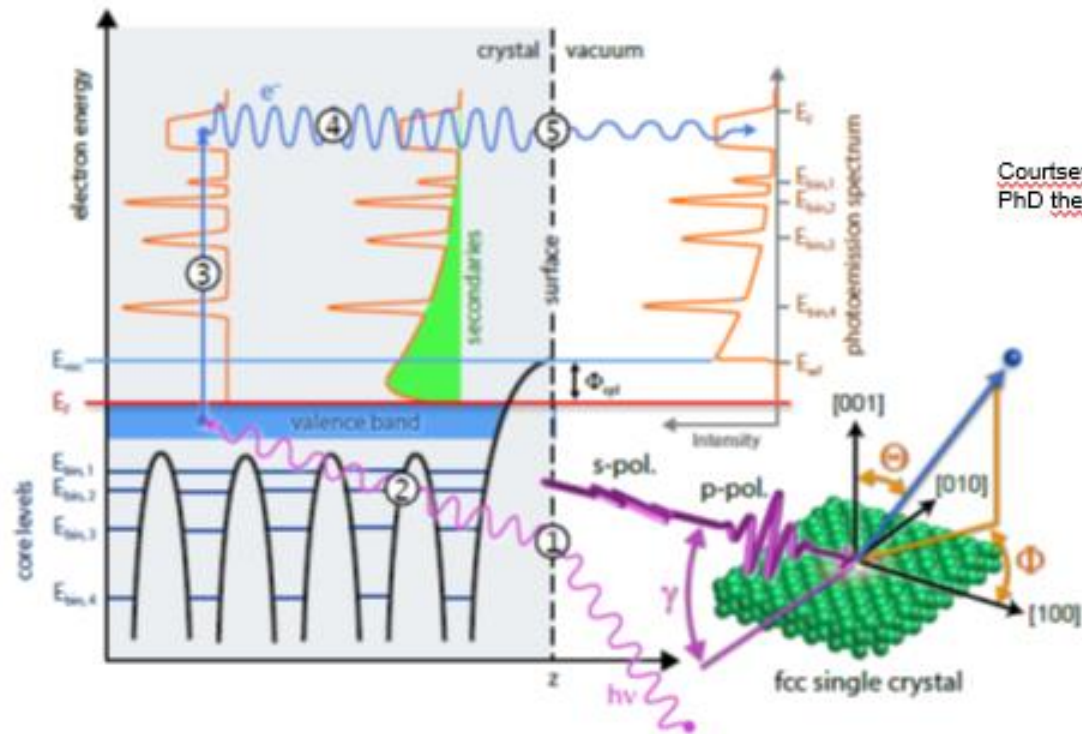
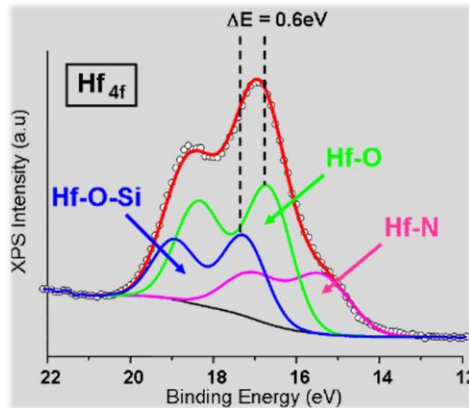
liten
cea tech

irig



- A photon-in/electron-out technique for analyzing occupied electronic states in matter
- Higher photon energies generate faster photoelectrons
- Chemical fingerprinting

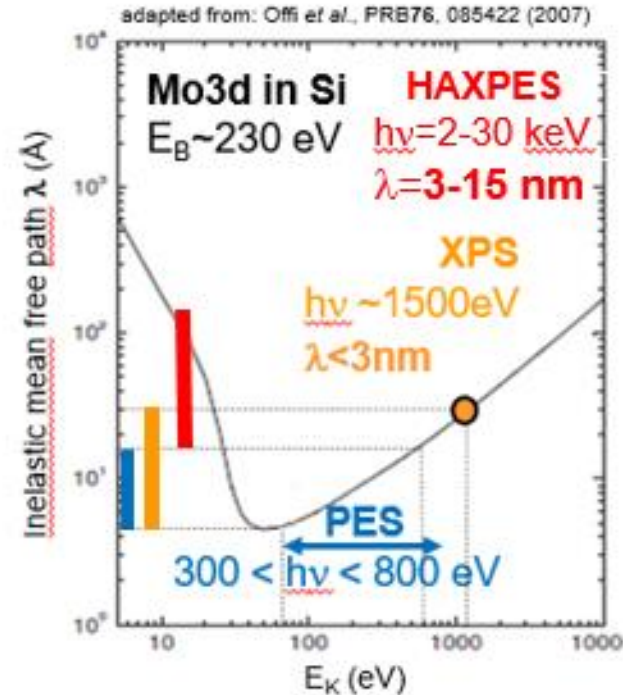
$$E_K = h\nu - E_B - e\Phi_s$$



Courtesy M. Patt,
PhD thesis, Jülich, 2018

Hard X-ray Photoelectron spectroscopy (HAXPES)

- Photon energies < 10 keV
- Developed at synchrotron facilities
- Since 2018: commercial lab-scale instruments



HAXPES

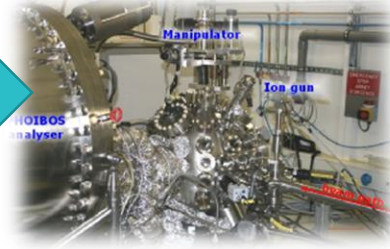
$h\nu \uparrow$

E_k (photo e^-) \uparrow

Mean free path \uparrow

Probing depth \uparrow

Synchrotrons



BM25

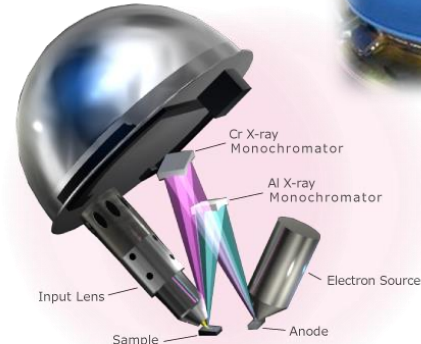


Lab-scale
instruments

Al K α (1486,6 eV)

Cr K α (5414,9 eV)

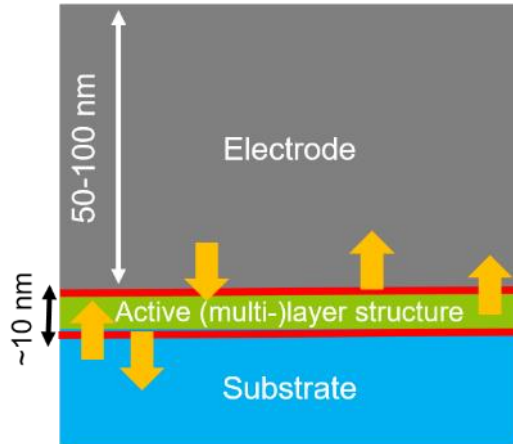
Ga K α (5414,9 eV)



HAXPES for analyzing buried interfaces

- Access to sub-surface of materials (<50 nm)
- **Device technology:** access to buried interfaces

Multi-layered materials In device technology



- Critical interfaces
- Inter-diffusion

• O. Renault - Lab-scale HAXPES @PFNC

2000: « The interface is the device »

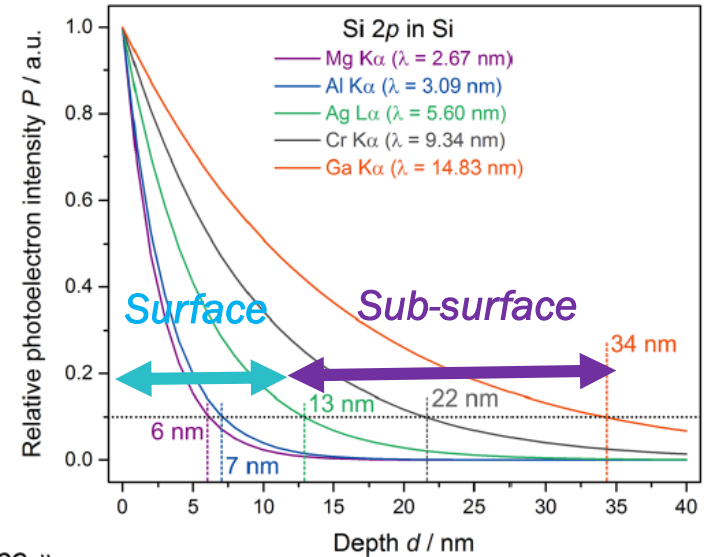
Herbert Kroemer, Nobel Lecture, dec. 8th, 2000



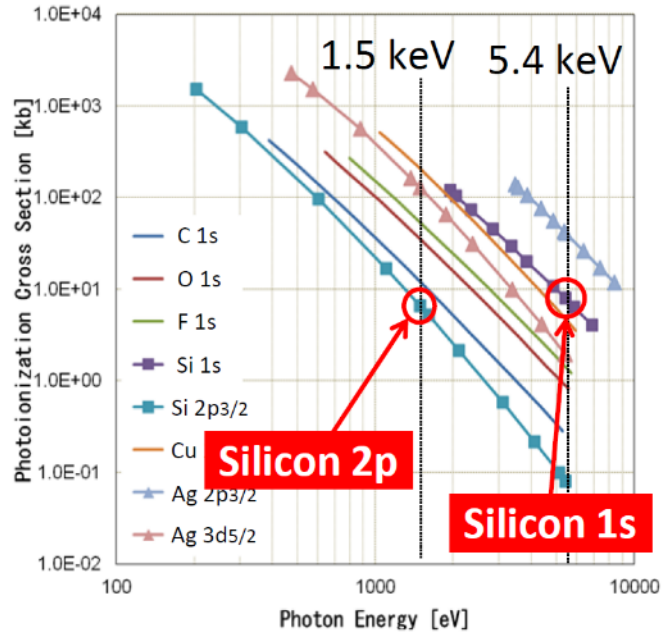
2012: « The interface is **still** the device »

Nat. Mater. **11**, 91

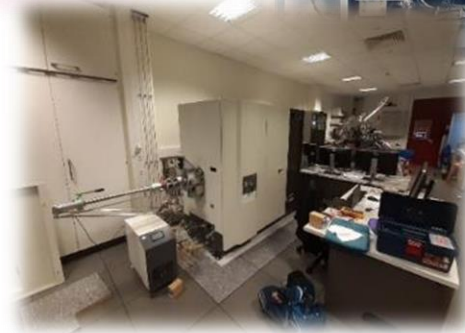
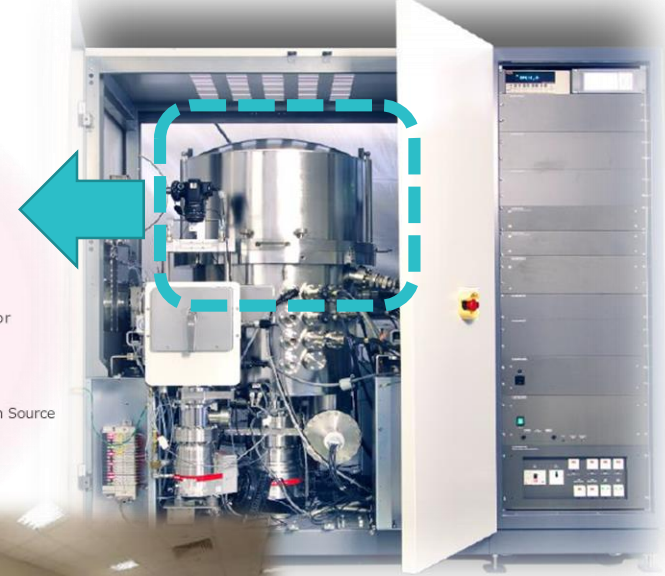
From: Regoutz et al., Rev. Sci. Instrum **89**, 073105 (2018).



- Two confocal X-ray micro-sources
- **Device technology:** no sensitivity loss for Si-based systems



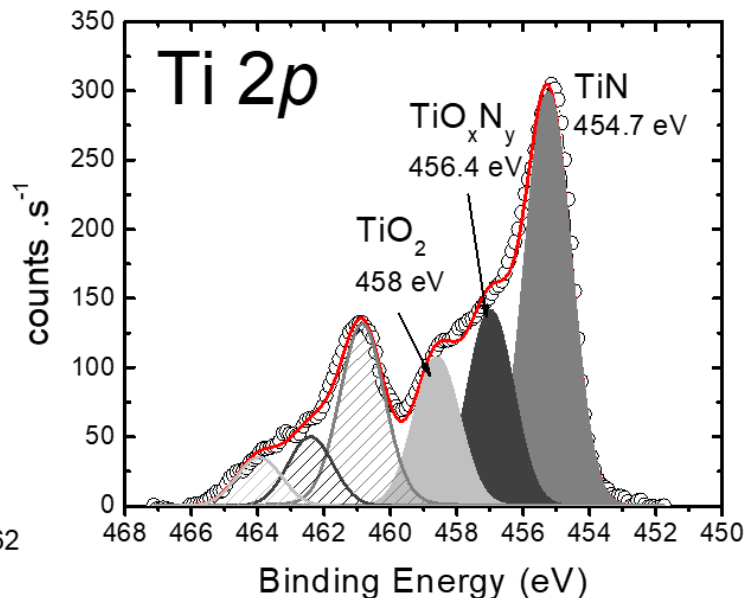
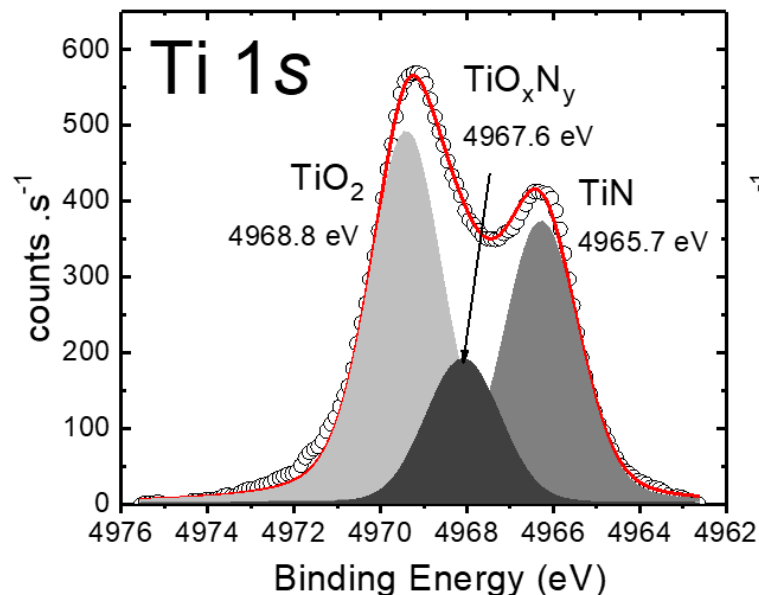
Quantex XPS/HAXPES spectrometer, ULVAC-PHI



Application case 1: depth profiling

➤ Different core-level lines provide variable probing depth

Photoelectron	Ti 1s	Ti 2p
Kinetic Energy (KE), eV	449	4962
Material	Pt (TiN)	Pt (TiN)
Inelastic mean-free path, nm	0.77 (1.08)	4.50 (6.93)



TiO_x surface layer

TiN 50nm

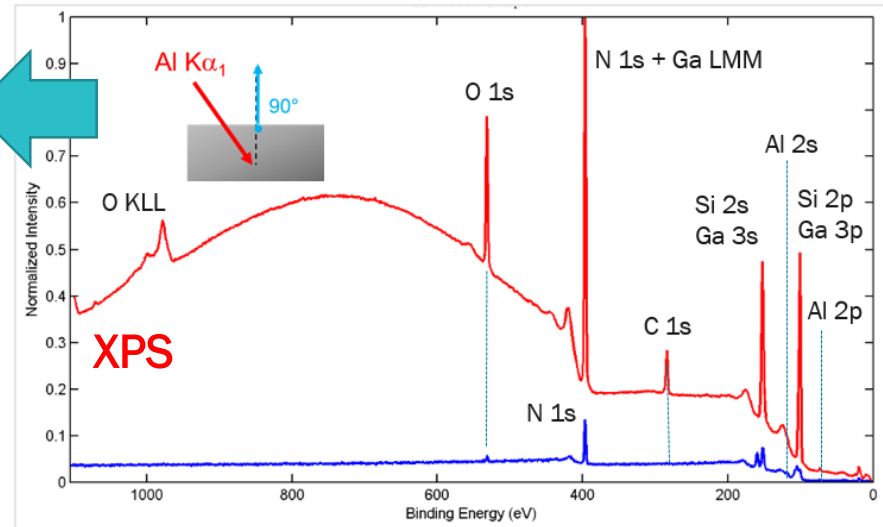
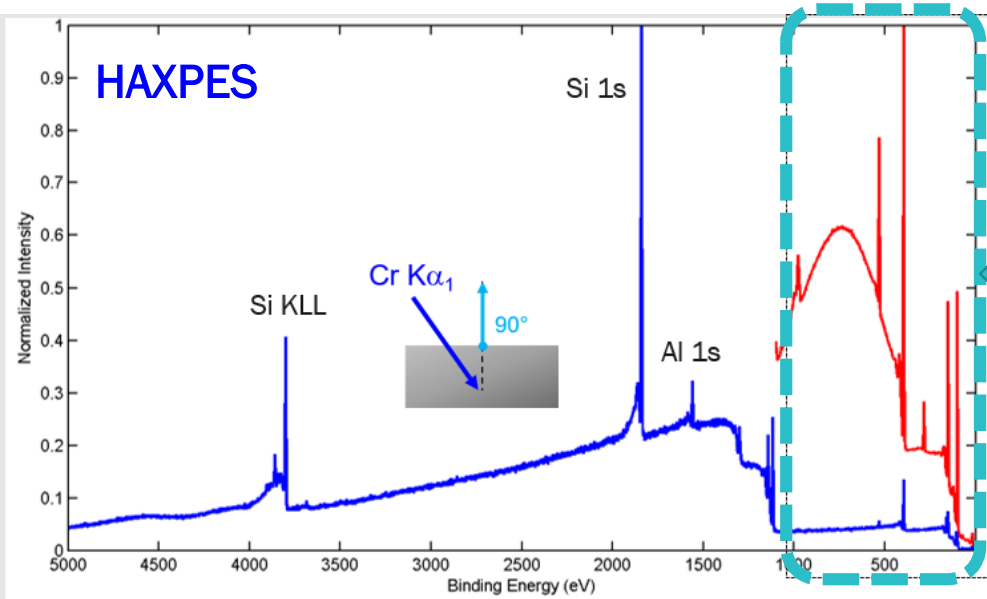
Si

O. Renault, E. Martinez et al., *Surf. Interface Anal.* **50**, 1158 (2018).

Application case 2: more accessible lines

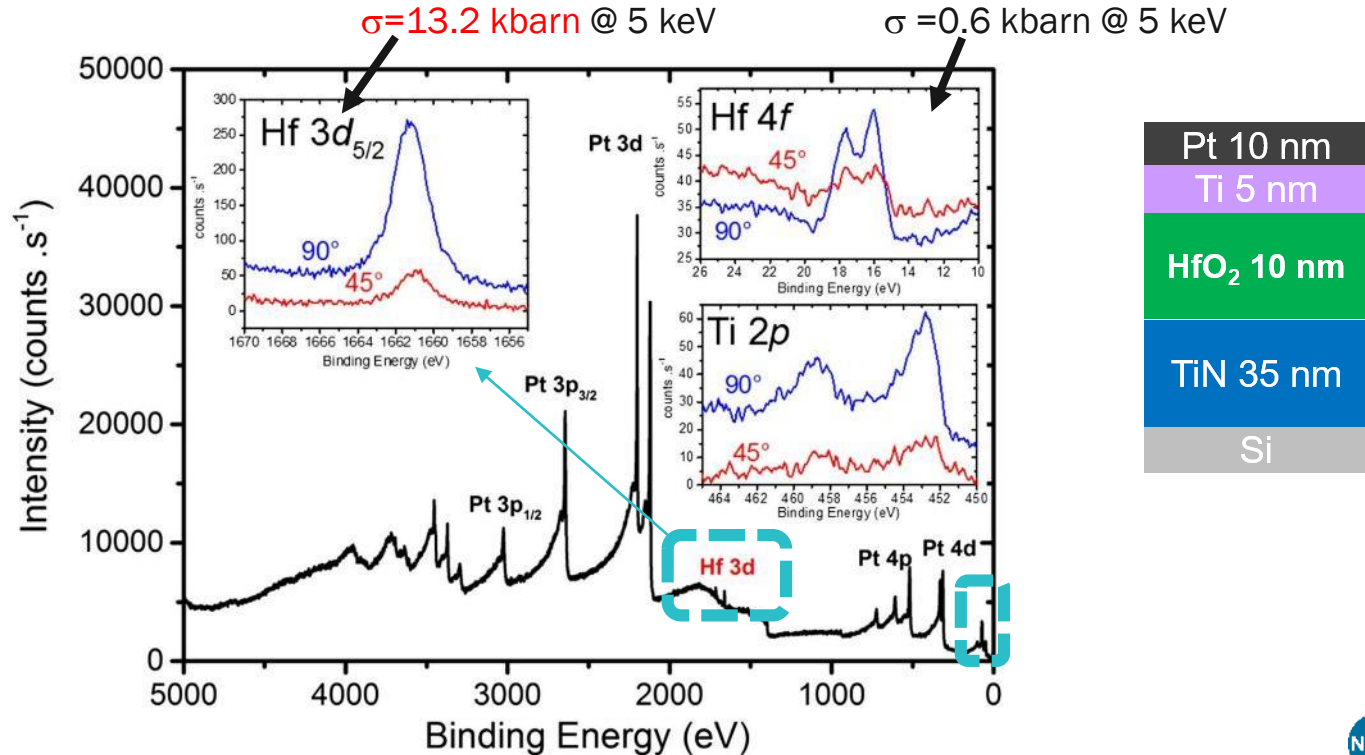
- Core-line overlapping in XPS: case of stacks of III/ IV-nitrides
- HAXPES enables analyzing isolated, high-energy levels

SiN 9 nm
AlN
GaN 2 μm
Si



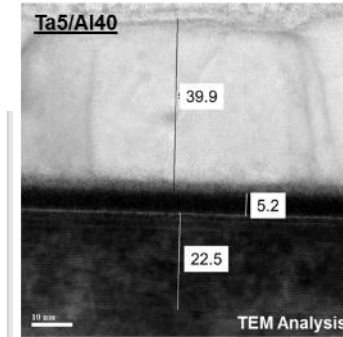
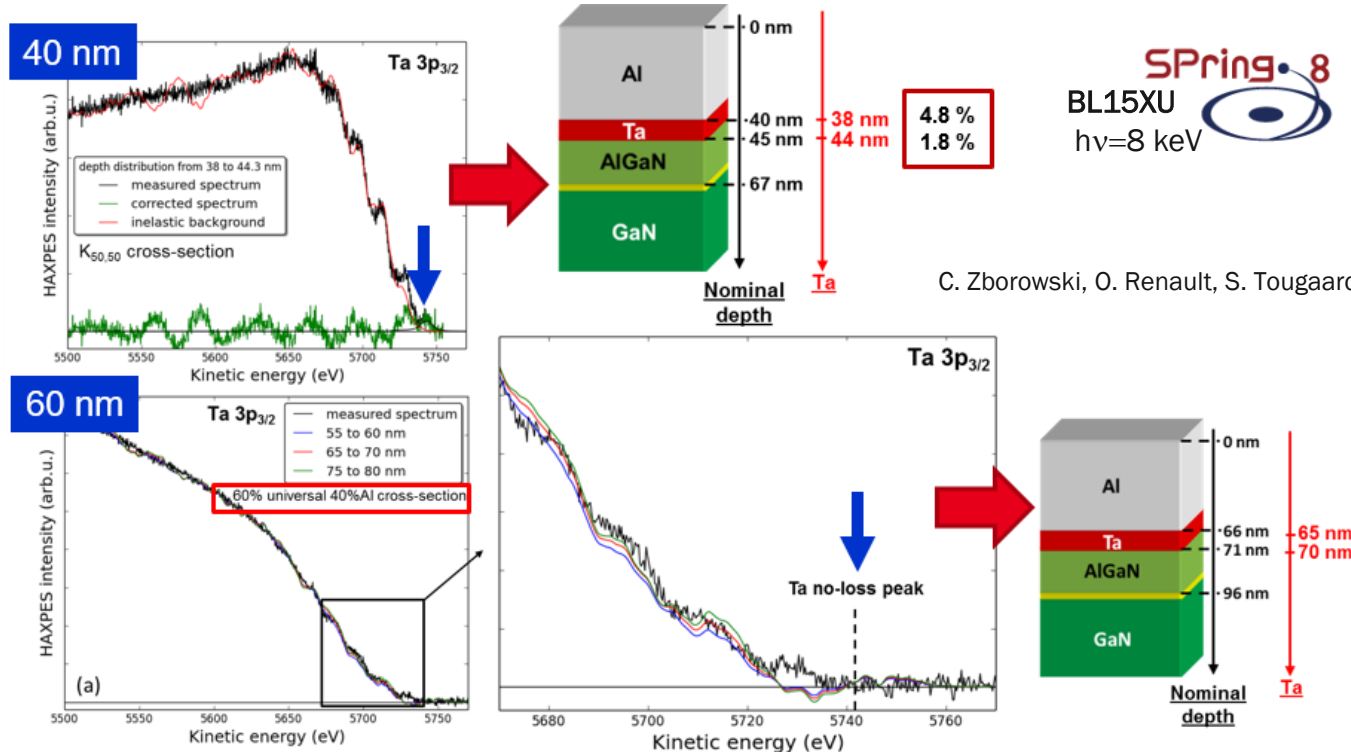
Application case 3: buried interfaces

- Resistive memory devices: access to critical oxide-electrode interface
- Available high energy core-line provides enhanced sensitivity (ionization cross-section)



Application case 4: inelastic background analysis

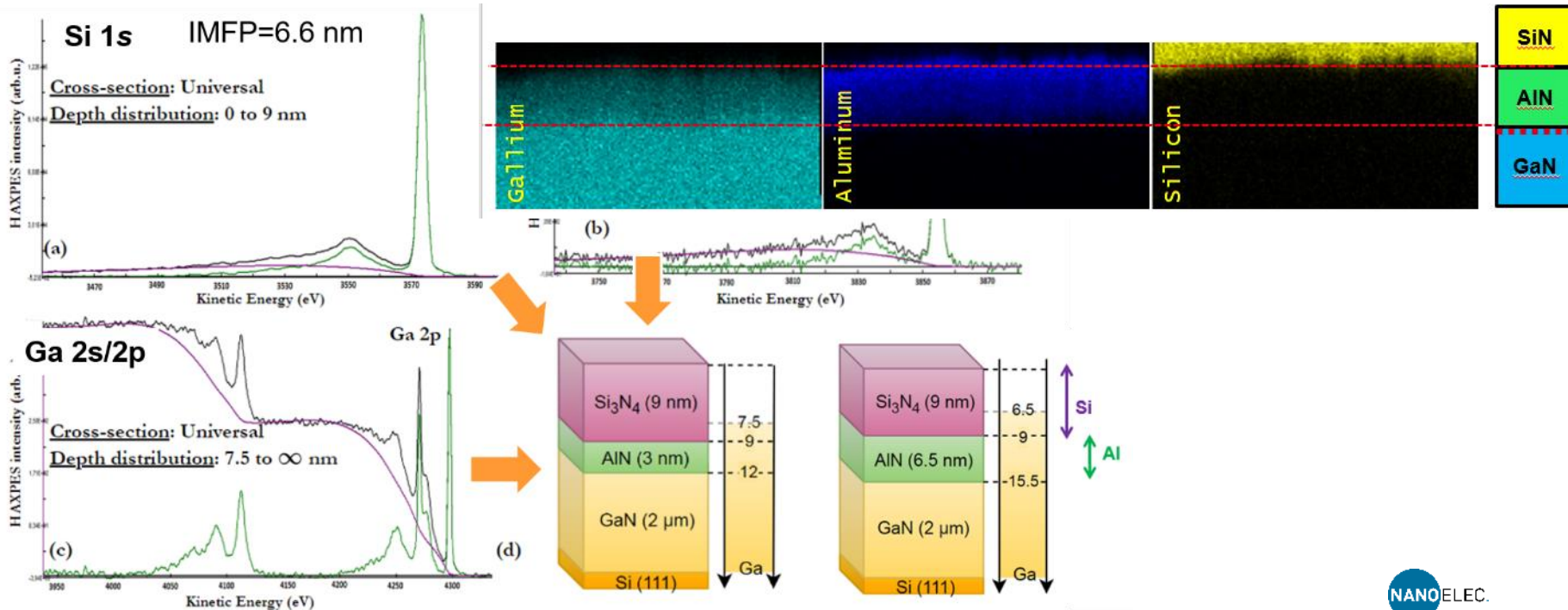
- Probing depth: $3 \times$ mean free path for elastic peaks (core-levels)
 $< 8 \times$ mean free path for energy losses (inelastic background)



C. Zborowski, O. Renault, S. Tougaard, *Appl. Surf. Sci.* **432** 60 (2018)

Application case 4: inelastic background analysis

- Probing depth: $< 8 \times$ mean free path for energy losses (inelastic background)
- Sub-surface diffusion phenomena accessible quantitatively



- Hard X-ray Photoelectron Spectroscopy is now getting in the lab
- It offers x3 probing depth (30 nm), up to 80 nm thanks to inelastic background analysis
- It is expected to become a standard tool for characterizing sub-surface phenomena in materials
- In device technology, buried interfaces are being analyzed non-destructively
- Synchrotron excitation will still remain useful for high-energy resolution needs

The results presented here were obtained at the Platform For NanoCharacterization, with the support of the « Recherche Technologique de Base » (RTB) program from french ministry of research.

Thank you for your attention



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